MEMORY cmos 2 × 512 K × 16 BIT SYNCHRONOUS DYNAMIC RAM

MB81F161622C-60/-70/-80/-80L

CMOS 2-Bank \times 524,288-Word \times 16 Bit Synchronous Dynamic Random Access Memory

DESCRIPTION

The Fujitsu MB81F161622C is a CMOS Synchronous Dynamic Random Access Memory (SDRAM) containing 16,777,216 memory cells accessible in an 16-bit format. The MB81F161622C features a fully synchronous operation referenced to a positive edge clock whereby all operations are synchronized at a clock input which enables high performance and simple user interface coexistence. The MB81F161622C SDRAM is designed to reduce the complexity of using a standard dynamic RAM (DRAM) which requires many control signal timing constraints, and may improve data bandwidth of memory as much as 5 times more than a conventional DRAM.

The MB81F161622C is ideally suited for laser printers, high resolution graphic adapters, accelerators and other applications where an extremely large memory and bandwidth are required and where a simple interface is needed.

PRODUCT LINE & FEATURES

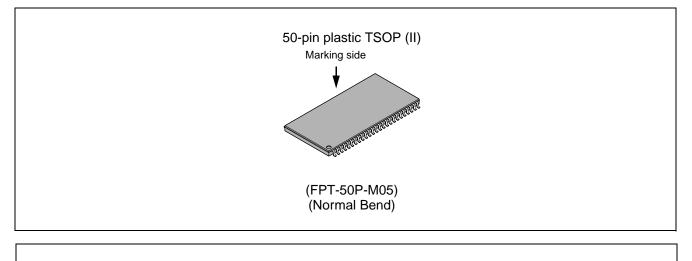
Parameter		MB81F161622C						
Falalleter	-60	-70	-80/-80L	(100MHz @CL=3)				
CL - trcd - trp	3 - 3 - 3 clk min.							
Clock Frequency (CL = 3)	167 MHz max.	143 MHz max.	125 MHz max.	100 MHz max.				
Burst Mode Cycle Time (CL = 3)	6.0 ns min.	7.0 ns min.	8.0 ns min.	10 ns min.				
Access Time From Clock (CL = 3)	5.5 ns max.	6 ns max.	6 ns max.	6 ns max.				
Operating Current	150 mA max.	130 mA max.	110 mA max.	90 mA max.				
Power Down Mode Current (Icc2P)	1 mA max.	1 mA max.	1 mA max.	1 mA max.				
Self Refresh Mode Current (Icc6)	1 mA max.	1 mA max.	1 mA / 400 µA max.	1 mA max.				

• Single +3.3 V Supply: +0.3 V / -0.15 V tolerance (-60) ±0.3 V tolerance (-70/-80/-80L)

- LVTTL compatible I/O interface
- 4 K refresh cycles every 64 ms
- Dual banks operation
- Burst read/write operation and burst read/single write operation capability

- Byte control by DQMU/DQML
- Programmable burst type, burst length, and CAS latency
- Auto-and Self-refresh (every 15.6 μs)
- CKE power down mode
- Output Enable and Input Data Mask
- 167 MHz/143MHz/125 MHz clock frequency

■ PACKAGE



Package and Ordering Information

- 50-pin plastic (400 mil) TSOP-II with normal bend leads, order as MB81F161622C-xxFN (Std. power) /-xxLFN (Low power)

■ PIN ASSIGNMENTS AND DESCRIPTIONS

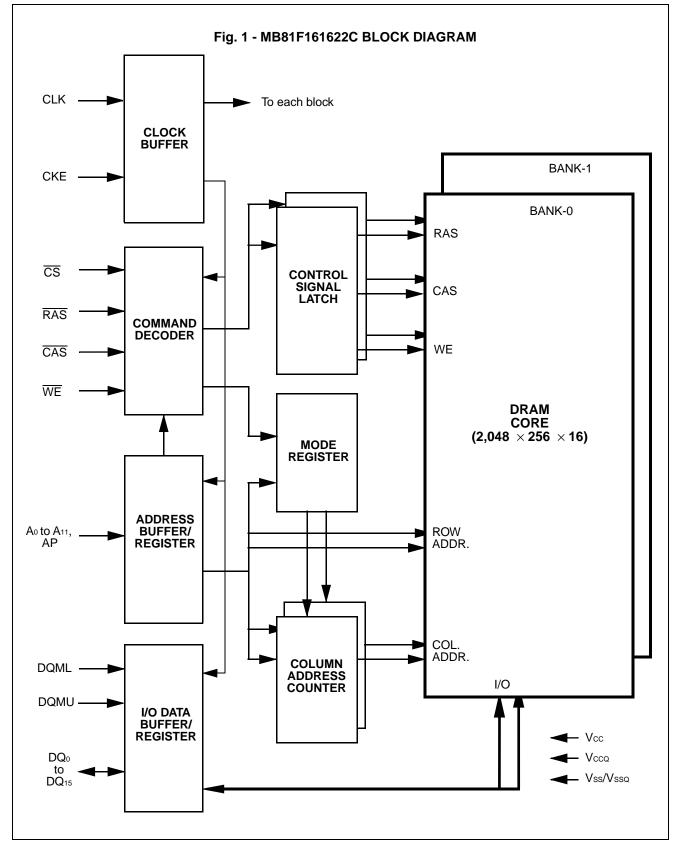
		Pin TSOP (II OP VIEW))		
<noi< td=""><td>mal Be</td><td>end: FPT-50</td><td>P-M</td><td>05></td><td></td></noi<>	mal Be	end: FPT-50	P-M	05>	
$\begin{array}{c} V_{CC} \\ D Q^{a} \\ Q^{a} \\$	$\begin{array}{c} 1 \\ 2 \\ 3 \\ 4 \\ 5 \\ 6 \\ 7 \\ 8 \\ 9 \\ 10 \\ 11 \\ 12 \\ 13 \\ 14 \\ 15 \\ 16 \\ 17 \\ 18 \\ 19 \\ 20 \\ 21 \\ 22 \\ 23 \\ 24 \\ 25 \end{array}$		50 49 48 47 46 45 44 43 42 41 40 39 8 37 36 33 32 31 30 29 8 27 26		Vss DQ15 DQ14 Vssa DQ13 DQ12 Vcca DQ12 Vcca DQ10 Vssa DQ3 DQ4 Vcca DQ0 DQ4 Vcca DQ0 DQ8 Vcca DQ0 A8 A7 A8 A7 A8 A7 A8 A7 A8 A7 A8 A7 A8 A7 A8 A7 A8 A7 A8 A7 A8 A7 A8 A7 A8 A7 A8 A7 A8 A7 A8 A7 A8 A7 A8 A7 A7 A8 A7 A7 A8 A7 A7 A8 A7 A7 A8 A7 A7 A8 A7 A7 A8 A7 A7 A7 A7 A7 A7 A7 A7 A7 A7 A7 A7 A7

(Marking side)

Pin Number	Symbol	Description
1, 7, 13, 25, 38, 44	Vcc, Vccq	Supply Voltage
2, 3, 5, 6, 8, 9, 11, 12, 39, 40, 42, 43, 45, 46, 48, 49	DQ ₀ to DQ ₁₅	Data I/O • Lower Byte: DQ ₀ to DQ ₇ • Upper Byte: DQ ₈ to DQ ₁₅
4, 10, 26, 41, 47, 50	Vss, Vssq*	Ground
33, 37	DU	Don't use (leave open)
15	WE	Write Enable
16	CAS	Column Address Strobe
17	RAS	Row Address Strobe
18	CS	Chip Select
19	A11 (BA)	Bank Select
20	AP	Auto Precharge Enable
20, 21, 22, 23, 24, 27, 28, 29, 30, 31, 32	A ₀ to A ₁₀	Address • Row: A₀ to A₁₀ Input • Column: A₀ to A₂
34	CKE	Clock Enable
35	CLK	Clock Input
14, 36	DQML, DQMU	Input Mask/Output Enable

* : These pins are connected internally in the chip.

BLOCK DIAGRAM



■ FUNCTIONAL TRUTHAL TABLE (Note *1)

COMMAND TRUTH TABLE Notes *2,*3, and *4

Function	Notes	Symbol	Cl	ΚE	CS	RAS		WE	A 11	A 10	A9, A8	A ₇ to
runction	NOLES	Symbol	n-1	n	03	NA3	CAS	VVL	(BA)	(AP)	A9, A8	A ₀
Device Deselect	*5	DESL	Н	Х	Н	Х	Х	Х	Х	Х	Х	Х
No Operation	*5	NOP	Н	Х	L	Н	Н	Н	Х	Х	Х	Х
Burst Stop		BST	Н	Х	L	Н	Н	L	Х	Х	Х	Х
Read	*6	READ	Н	Х	L	Н	L	Н	V	L	Х	V
Read with Auto-precharge	*6	READA	Н	Х	L	Н	L	Н	V	Н	Х	V
Write	*6	WRIT	Н	Х	L	Н	L	L	V	L	Х	V
Write with Auto-precharge	*6	WRITA	Н	Х	L	Н	L	L	V	Н	Х	V
Bank Active (RAS)	*7	ACTV	Н	Х	L	L	Н	Н	V	V	V	V
Precharge Single Bank		PRE	Н	Х	L	L	Н	L	V	L	Х	Х
Precharge All Banks		PALL	Н	Х	L	L	Н	L	Х	Н	Х	Х
Mode Register Set	*8,*9	MRS	Н	Х	L	L	L	L	L	L	V	V

Notes: *1. V = Valid, L = Logic Low, H = Logic High, X = either L or H

*2. All commands assume no CSUS command on previous rising edge of clock.

*3. All commands are assumed to be valid state transitions.

*4. All inputs are latched on the rising edge of clock.

*5. NOP and DESL commands have the same effect on the part. Unless specifically noted, NOP will represent both NOP and DESL command in later descriptions.

*6. READ, READA, WRIT, and WRITA commands should only be issued after the corresponding bank has been activated (ACTV command). Refer to STATE DIAGRAM.

*7. ACTV command should only be asserted after corresponding bank has been precharged (PRE or PALL command).

*8. Required after power up. Refer to POWER-UP INITIALIZATION in page 19.

*9. MRS command should only be issued after all banks have been precharged (PRE or PALL command). Refer to STATE DIAGRAM.

DQM TRUTH TABLE

Function	Command	CI	KE	DQML	DQMU
T unction	Command	n-1	n	DQINL	DQINO
Data Write/Output Enable for Lower Byte	ENBL L	Н	Х	L	Х
Data Write/Output Enable for Upper Byte	ENBL U	Н	Х	Х	L
Data Mask/Output Disable for Lower Byte	MASK L	Н	Х	Н	Х
Data Mask/Output Disable for Upper Byte	MASK U	Н	Х	Х	Н

CKE TRUTH TABLE

Current	Function	Notes	Symbol	C	٢E	CS	RAS	CAS	WE	A 11	A 10	A∍to
State	runction	NOLES	Symbol	n-1	n	03	NA3	CAS	VVL	(BA)	(AP)	A ₀
Bank Active	Clock Suspend Mode Entry	y *1	CSUS	Н	L	Х	Х	Х	Х	Х	Х	Х
Any Except to Idle	Clock Suspend Continue	*1		L	L	х	х	х	Х	х	х	х
Clock Suspend	Clock Suspend Mode Exit			L	н	Х	Х	Х	Х	х	Х	х
Idle	Auto-refresh Command	*2	REF	Н	Н	L	L	L	Н	Х	Х	Х
Idle	Self-refresh Entry	*2,*3	SELF	Н	L	L	L	L	Н	Х	Х	Х
Self-refresh	Self-refresh Exit		SELFX	L	Н	L	Н	Н	Н	Х	Х	Х
Sell-reflesh	Sell-Tellesh Exit		JELFA	L	Н	Н	Х	Х	Х	Х	Х	Х
Idle	Power Down Entry	*3	PD	Н	L	L	Н	Н	Н	Х	Х	Х
lule	Power Down Entry	3	FD	Н	L	Н	Х	Х	Х	Х	Х	Х
	Power Down Evit			L	Н	L	Н	Н	Н	Х	Х	Х
Power Down	Power Down Exit			L	Н	Н	Х	Х	Х	Х	Х	Х

Notes: *1. The CSUS command requires that at least one bank is active. Refer to STATE DIAGRAM. NOP or DESL commands should only be issued after CSUS and PRE (or PALL) commands asserted at same time.

*2. REF and SELF commands should only be issued after all banks have been precharged (PRE or PAL command). Refer to STATE DIAGRAM.

*3. Self and PD commands should only be issued after the last data have been appeared on DQ.

Current State	CS	RAS	CAS	WE	Addr	Command	Function Notes
Idle	Н	Х	Х	Х	Х	DESL	NOP
	L	Н	Н	Н	Х	NOP	NOP
	L	Н	Н	L	Х	BST	NOP
	L	Н	L	Н	BA, CA, AP	READ/READA	Illegal *2
	L	Н	L	L	BA, CA, AP	WRIT/WRITA	Illegal *2
	L	L	Н	Н	BA, RA	ACTV	Bank Active after tRCD
	L	L	Н	L	BA, AP	PRE/PALL	NOP
	L	L	L	Н	Х	REF/SELF	Auto-refresh or Self-refresh *3,*6
	L	L	L	L	MODE	MRS	Mode Register Set (Idle after tRSC) *3,*7
Bank Active	Н	Х	Х	Х	Х	DESL	NOP
	L	Н	Н	Н	Х	NOP	NOP
	L	Н	Н	L	Х	BST	NOP
	L	Н	L	Н	BA, CA, AP	READ/READA	Begin Read; Determine AP
	L	Н	L	L	BA, CA, AP	WRIT/WRITA	Begin Write; Determine AP
	L	L	Н	Н	BA, RA	ACTV	Illegal *2
	L	L	Н	L	BA, AP	PRE/PALL	Precharge; Determine Precharge Type
	L	L	L	Н	Х	REF/SELF	Illegal
	L	L	L	L	MODE	MRS	Illegal

OPERATION COMMAND TABLE (Applicable to single bank) Note *1

(Continued)

Current State	CS	RAS	CAS	WE	Addr	Command	Function Note	s
Read	Н	х	х	х	х	DESL	NOP (Continue Burst to End \rightarrow Bank Active)	
	L	н	Н	Н	х	NOP	NOP (Continue Burst to End \rightarrow Bank Active)	
	L	Н	н	L	Х	BST	Burst Stop \rightarrow Bank Active	
	L	н	L	Н	BA, CA, AP	READ/READA	Terminate Burst, New Read; Determine AP	
	L	н	L	L	BA, CA, AP	WRIT/WRITA	Terminate Burst, Start Write;	*4
	L	L	Н	Н	BA, RA	ACTV	Illegal *	*2
	L	L	Н	L	BA, AP	PRE/PALL	Terminate Burst, Precharge; \rightarrow Idle Determine Precharge Type	
	L	L	L	Н	Х	REF/SELF	Illegal	
	L	L	L	L	MODE	MRS	Illegal	
Write	н	x	х	х	х	DESL	NOP (Continue Burst to End \rightarrow Bank Active)	
	L	н	н	Н	х	NOP	NOP (Continue Burst to End \rightarrow Bank Active)	
	L	Н	н	L	Х	BST	Burst Stop \rightarrow Bank Active	
	L	н	L	Н	BA, CA, AP	READ/READA	Terminate Burst, Start Read; * Determine AP	*4
	L	н	L	L	BA, CA, AP	WRIT/WRITA	Terminate Burst, New Write; Determine AP	
	L	L	Н	Н	BA, RA	ACTV	Illegal *	*2
	L	L	н	L	BA, AP	PRE/PALL	Terminate Burst, Precharge; Determine Precharge Type	
	L	L	L	Н	Х	REF/SELF	Illegal	
	L	L	L	L	MODE	MRS	Illegal	

(Continued)

Current State	CS	RAS	CAS	WE	Addr	Command	Function	Notes
Read with Auto- precharge	Н	х	х	х	х	DESL	NOP (Continue Burst to End \rightarrow Precharge \rightarrow Idle)	
precharge	L	н	Н	Н	х	NOP	NOP (Continue Burst to End \rightarrow Precharge \rightarrow Idle)	
	L	н	Н	L	Х	BST	Illegal	
	L	н	L	Н	BA, CA, AP	READ/READA	Illegal	*2
	L	н	L	L	BA, CA, AP	WRIT/WRITA	Illegal	*2
	L	L	Н	Н	BA, RA	ACTV	Illegal	*2
	L	L	Н	L	BA, AP	PRE/PALL	Illegal	*2
	L	L	L	Н	Х	REF/SELF	Illegal	
	L	L	L	L	MODE	MRS	Illegal	
Write with Auto-	Н	х	х	Х	х	DESL	NOP (Continue Burst to End \rightarrow Precharge \rightarrow Idle)	
precharge	L	н	Н	Н	х	NOP	NOP (Continue Burst to End \rightarrow Precharge \rightarrow Idle)	
	L	н	Н	L	Х	BST	Illegal	
	L	н	L	Н	BA, CA, AP	READ/READA	Illegal	*2
	L	н	L	L	BA, CA, AP	WRIT/WRITA	Illegal	*2
	L	L	Н	Н	BA, RA	ACTV	Illegal	*2
	L	L	Н	L	BA, AP	PRE/PALL	Illegal	*2
	L	L	L	Н	х	REF/SELF	Illegal	
	L	L	L	L	MODE	MRS	Illegal	

(Continued)

Current State	CS	RAS	CAS	WE	Addr	Command	Function	Notes
Precharge	Н	Х	Х	Х	Х	DESL	NOP (Idle after tRP)	
	L	н	Н	Н	Х	NOP	NOP (Idle after tRP)	
	L	н	Н	L	Х	BST	Illegal	
	L	н	L	Н	BA, CA, AP	READ/READA	Illegal	*2
	L	н	L	L	BA, CA, AP	WRIT/WRITA	Illegal	*2
	L	L	Н	Н	BA, RA	ACTV	Illegal	*2
	L	L	Н	L	BA, AP	PRE/PALL	NOP (PALL may effect other bank)	*5
	L	L	L	Н	Х	REF/SELF	Illegal	
	L	L	L	L	MODE	MRS	Illegal	
Bank	н	Х	Х	Х	Х	DESL	NOP (Bank Active after tRCD)	
Activating	L	н	Н	Н	Х	NOP	NOP (Bank Active after tRCD)	
	L	н	Н	L	Х	BST	NOP (Bank Active after tRCD)	
	L	н	L	Н	BA, CA, AP	READ/READA	Illegal	*2
	L	н	L	L	BA, CA, AP	WRIT/WRITA	Illegal	*2
	L	L	Н	Н	BA, RA	ACTV	Illegal	*2
	L	L	н	L	BA, AP	PRE/PALL	Illegal	*2
	L	L	L	Н	Х	REF/SELF	Illegal	
	L	L	L	L	MODE	MRS	Illegal	

(Continued)

Current State	CS	RAS	CAS	WE	Addr	Command	Function Notes
Refreshing	Н	Х	Х	Х	х	DESL	NOP (Idle after trc)
	L	Н	Н	Х	Х	NOP/BST	NOP (Idle after tRC)
	L	н	L	х	Х	READ/READA/ WRIT/WRITA	Illegal
	L	L	Н	х	Х	ACTV/PRE/ PALL	Illegal
	L	L	L	х	Х	REF/SELF/ MRS	Illegal
Mode Register	Н	Х	Х	Х	Х	DESL	NOP (Idle after trsc)
Setting	L	Н	Н	Н	Х	NOP	NOP (Idle after t _{RSC})
	L	Н	Н	L	Х	BST	Illegal
	L	н	L	х	Х	READ/READA/ WRIT/WRITA	Illegal
	L	L	х	х	Х	ACTV/PRE/ PALL/REF/ SELF/MRS	Illegal

ABBREVIATIONS:

RA = Row Address

BA = Bank Address

CA = Column Address AP = Auto Precharge

Notes: *1. All entries assume the CKE was High during the proceeding clock cycle and the current clock cycle. Illegal means don't used command. If used, power up sequence be asserted after power shout down.

- *2. Illegal to bank in specified state; entry may be legal in the bank specified by BA, depending on the state of that bank.
- *3. Illegal if any bank is not idle.
- *4. Must satisfy bus contention, bus turn around, and/or write recovery requirements. Refer to TIMING DIAGRAM - 11 & - 12.
- *5. NOP to bank precharging or in idle state. May precharge bank specified by BA (and AP).
- *6. SELF command should only be issued after the last read data have been appeared on DQ.
- *7. MRS command should only be issued on condition that all DQ are in Hi-Z.

COMMAND TRUTH TABLE FOR CKE Note *1

Current State	CKE n-1	CKE n	CS	RAS	CAS	WE	Addr	Function Notes
Self- refresh	Н	Х	Х	Х	Х	Х	х	Invalid
Tellesii	L	Н	н	х	х	х	х	Exit Self-refresh (Self-refresh Recovery \rightarrow Idle after t _{RC})
	L	Н	L	н	Н	Н	х	Exit Self-refresh (Self-refresh Recovery \rightarrow Idle after t _{RC})
	L	Н	L	н	Н	L	х	Illegal
	L	Н	L	Н	L	Х	Х	Illegal
	L	Н	L	L	Х	Х	Х	Illegal
	L	L	Х	Х	Х	Х	Х	NOP (Maintain Self-refresh)
Self- refresh	L	Х	Х	Х	Х	Х	Х	Invalid
Recovery	Н	Н	Н	Х	Х	Х	Х	Idle after trc
	Н	Η	L	Н	Н	Н	Х	Idle after trc
	Н	Η	L	Н	Н	L	Х	Illegal
	Н	Η	L	Н	L	Х	Х	Illegal
	Н	Н	L	L	Х	Х	Х	Illegal
	Н	Н	Х	Х	Х	Х	Х	Illegal
	Н	L	Х	Х	Х	Х	Х	Illegal *2

(Continued)

Current State	CKE n-1	CKE n	CS	RAS	CAS	WE	Addr	Function Notes			
Power Down	Н	Х	Х	Х	Х	Х	Х	Invalid			
DOwn	L	Н	Н	Х	Х	Х	Х	Exit Power Down Mode \rightarrow Idle			
	L	Н	L	Н	Н	Н	Х	Exit Power Down Mode \rightarrow Idle			
	L	L	Х	Х	Х	Х	Х	NOP (Maintain Power Down Mode)			
	L	Н	L	L	Х	Х	Х	Illegal			
	L	Н	L	Н	L	Х	Х	Illegal			
Both Banks	Н	Н	Н	Х	Х	Х	MODE	Refer to the Operation Command Table			
Idle	Н	Н	L	Н	Х	Х	MODE	Refer to the Operation Command Table			
	Н	Н	L	L	Н	Х	MODE	Refer to the Operation Command Table			
	Н	Н	L	L	L	Н	Х	Auto-refresh			
	Н	Н	L	L	L	L	MODE	Refer to the Operation Command Table			
	Н	L	Н	Х	Х	Х	Х	Power Down			
	Н	L	L	Н	Н	Н	Х	Power Down			
	Н	L	L	Н	Н	L	Х	Illegal			
	Н	L	L	Н	L	Х	Х	Illegal			
	Н	L	L	L	Н	Х	Х	Illegal			
	Н	L	L	L	L	Н	Х	Self-refresh *3			
	Н	L	L	L	L	L	Х	Illegal			
	L	Х	Х	Х	Х	Х	Х	Invalid			

(Continued)

Current State	CKE n-1	CKE n	CS	RAS	CAS	WE	Addr	Function Notes			
Bank Active Bank	Н	н	Х	Х	Х	Х	Х	Refer to the Operation Command Table			
Activating Read/Write	Н	L	Х	Х	Х	Х	Х	Begin Clock Suspend Next Cycle			
	L	Х	Х	Х	Х	Х	Х	Invalid			
Clock Suspend	Н	Х	Х	Х	Х	Х	Х	Invalid			
Suspend	L	н	Х	Х	Х	Х	Х	Exit Clock Suspend Next Cycle			
	L	L	Х	Х	Х	Х	Х	Maintain Clock Suspend			
Any State Other Than	Н	н	Х	Х	Х	Х	Х	Refer to the Operation Command Table			
Listed Above	Н	L	Х	Х	Х	Х	Х	Illegal			
	L	Х	Х	Х	Х	Х	Х	Invalid			

Notes: *1. All entries in COMMAND TRUTH TABLE FOR CKE are specified at CKE(n) state and CKE input from CKE(n–1) to CKE(n) state must satisfy corresponding set up and hold time for CKE.

*2. CKE should be held High for t_{RC} period.

*3. SELF command should only be issued after the last data have been appeared on DQ.

■ FUNCTIONAL DESCRIPTION

SDRAM BASIC FUNCTION

Three major differences between this SDRAM and conventional DRAMs are: synchronized operation, burst mode, and mode register.

The **synchronized operation** is the fundamental difference. An SDRAM uses a clock input for the synchronization, where the DRAM is basically asynchronous memory although it has been using two clocks, RAS and CAS. Each operation of DRAM is determined by their timing phase differences while each operation of SDRAM is determined by commands and all operations are referenced to a positive clock edge. Fig.2 shows the basic timing diagram differences between SDRAMs and DRAMs.

The **burst mode** is a very high speed access mode utilizing an internal column address generator. Once a column addresses for the first access is set, following addresses are automatically generated by the internal column address counter.

The **mode register** is to justify the SDRAM operation and function into desired system conditions. MODE REGISTER TABLE shows how SDRAM can be configured for system requirement by mode register programming.

CLOCK (CLK) AND CLOCK ENABLE (CKE)

All input and output signals of SDRAM use register type buffers. A CLK is used as a trigger for the register and internal burst counter increment. All inputs are latched by a positive edge of CLK. All outputs are validated by the CLK. CKE is a high active clock enable signal. When CKE = Low is latched at a clock input during active cycle, the next clock will be internally masked. During idle state (all banks have been precharged), the Power Down mode(standby) is entered with CKE = Low and this will make extremely low standby current.

CHIP SELECT (CS)

 \overline{CS} enables all commands inputs, \overline{RAS} , \overline{CAS} , and \overline{WE} , and address input. When \overline{CS} is High, command signals are negated but internal operation such as burst cycle will not be suspended. If such a control isn't needed, \overline{CS} can be tied to ground level.

COMMAND INPUTS (RAS, CAS and WE)

Unlike a conventional DRAM, RAS, CAS, and WE do not directly imply SDRAM operation, such as Row address strobe by RAS. Instead, each combination of RAS, CAS, and WE input in conjunction with CS input at a rising edge of the CLK determines SDRAM operation. Refer to FUNCTIONAL TRUTH TABLE in page 5.

ADDRESS INPUTS (Ao to A1o)

Address input selects an arbitrary location of a total of 524,288 words of each memory cell matrix. A total of 19 address input signals are required to decode such a matrix. SDRAM adopts an address multiplexer in order to reduce the pin count of the address line. At a Bank Active command (ACTV), 11 Row addresses are initially latched and the remainder of 8 Column addresses are then latched by a Column address strobe command of either a Read command (READ or READA) or Write command (WRIT or WRITA).

BANK SELECT (A11)

This SDRAM has two banks and each bank is organized as 512 K words by 16-bit. Bank selection by A₁₁ occurs at Bank Active command (ACTV) followed by read (READ or READA), write (WRIT or WRITA), and precharge command (PRE).

DATA INPUTS AND OUTPUTS (DQ0 to DQ15)

Input data is latched and written into the memory at the clock following the write command input. Data output is obtained by the following conditions followed by a read command input:

- tRAC: from the bank active command when tRCD (min) is satisfied. (This parameter is reference only.)
- tcac: from the read command when tRCD is greater than tRCD (min).(This parameter is reference only.)
- tac : from the clock edge after t_{RAC} and t_{CAC}

The polarity of the output data is identical to that of the input. Data is valid between access time (determined by the three conditions above) and the next positive clock edge (toH).

DATA I/O MASK (DQML/DQMU)

DQML and DQMU are active high enable inputs and have an output disable and input mask function. During burst cycle and when DQML/DQMU = High is latched by a clock, input is masked at the same clock and output will be masked at the second clock later while internal burst counter will increment by one or will go to the next stage depending on burst type.

DQML controls lower byte (DQ₀ to DQ₇) and DQMU controls upper byte (DQ₈ to DQ₁₅).

BURST MODE OPERATION AND BURST TYPE

The burst mode provides faster memory access. The burst mode is implemented by keeping the same Row address and by automatic strobing column address. Access time and cycle time of Burst mode is specified as t_{AC} and t_{CK}, respectively. The internal column address counter operation is determined by a mode register which defines burst type and burst count length of 1,2,4 or 8 bits of boundary. In order to terminate or to move from the current burst mode to the next stage while the remaining burst count is more than 1, the following combinations will be required:

Current Stage	Next Stage	Ν	Nethod (Assert the following command)
Burst Read	Burst Read	Read Comma	ind
Burst Read	Burst Write	1st Step	Mask Command (Normally 3 clock cycles)
Buist Read	Burst write	2nd Step	Write Command after Iowd
Burst Write	Burst Write	Write Comma	ind
Burst Write	Burst Read	Read Comma	Ind
Burst Read	Precharge	Precharge Co	ommand
Burst Write	Precharge	Precharge Co	ommand

The burst type can be selected either sequential or interleave mode if burst length is 2,4 or 8. The sequential mode is an incremental decoding scheme within a boundary address to be determined by count length, it assigns +1 to the previous (or initial) address until reaching the end of boundary address and then wraps round to least significant address(=0). The interleave mode is a scrambled decoding scheme for A_0 and A_2 . If the first access of column address is even (0), the next address will be odd (1), or vice-versa.

(Continued)

When the full burst operation is executed at single write mode, Auto-precharge command is valid only at write operation.

The burst type can be selected either sequential or interleave mode. But only the sequential mode is usable to the full column burst. The sequential mode is an incremental decoding scheme within a boundary address to be determined by burst length, it assigns +1 to the previous (or initial) address until reaching the end of boundary address and then wraps round to least significant address(=0).

Burst Length	Stating Column Address A ₂ A ₁ A ₀	Sequential Mode	Interleave
2	X X 0	0 - 1	0 - 1
2	X X 1	1 - 0	1 - 0
	X 0 0	0 - 1 - 2 - 3	0 - 1 - 2 - 3
4	X 0 1	1 - 2 - 3 - 0	1 - 0 - 3 - 2
4	X 1 0	2 - 3 - 0 - 1	2 - 3 - 0 - 1
	X 1 1	3 - 0 - 1 - 2	3 - 2 - 1 - 0
	0 0 0	0 - 1 - 2 - 3 - 4 - 5 - 6 - 7	0 - 1 - 2 - 3 - 4 - 5 - 6 - 7
	0 0 1	1 - 2 - 3 - 4 - 5 - 6 - 7 - 0	1 - 0 - 3 - 2 - 5 - 4 - 7 - 6
	0 1 0	2 - 3 - 4 - 5 - 6 - 7 - 0 - 1	2 - 3 - 0 - 1 - 6 - 7 - 4 - 5
8	0 1 1	3 - 4 - 5 - 6 - 7 - 0 - 1 - 2	3 - 2 - 1 - 0 - 7 - 6 - 5 - 4
0	1 0 0	4 - 5 - 6 - 7 - 0 - 1 - 2 - 3	4 - 5 - 6 - 7 - 0 - 1 - 2 - 3
	1 0 1	5 - 6 - 7 - 0 - 1 - 2 - 3 - 4	5 - 4 - 7 - 6 - 1 - 0 - 3 - 2
	1 1 0	6 - 7 - 0 - 1 - 2 - 3 - 4 - 5	6 - 7 - 4 - 5 - 2 - 3 - 0 - 1
	1 1 1	7 - 0 - 1 - 2 - 3 - 4 - 5 - 6	7 - 6 - 5 - 4 - 3 - 2 - 1 - 0

FULL COLUMN BURST AND BURST STOP COMMAND (BST)

The full column burst is an option of burst length and available only at sequential mode of burst type. This full column burst mode is repeatedly access to the same column. If burst mode reaches end of column address, then it wraps round to first column address (=0) and continues to count until interrupted by the news Read (READ) /Write (WRIT), Precharge (PRE), or Burst Stop (BST) command. The selection of Auto-precharge option is illegal during the full column burst operation except write command at BURST READ & SINGLE WRITE mode.

The BST command is applicable to terminated burst operation. If the BST command is asserted burst mode, its operation is terminated immediately and the internal state moves to Bank Active.

When read mode is interrupted by BST command, the output will be in High-Z.

For the detail rule, please refer to TIMING DIAGRAM-8.

When write mode is interrupted by BST command, the data to be applied at the same time with BST command will be ignored.

BURST READ & SINGLE WRITE

The burst read and single write mode provides single word write operation regardless of its burst length. In this mode, burst read operation does not affected by this mode.

PRECHARGE AND PRECHARGE OPTION (PRE, PALL)

SDRAM memory core is the same as conventional DRAMs', requiring precharge and refresh operations. Precharge rewrites the bit line and to reset the internal Row address line and is executed by the Precharge command (PRE). With the Precharge command, SDRAM will automatically be in standby state after precharge time (t_{RP}).

The precharged bank is selected by combination of AP and A₁₁ when Precharge command is asserted. If AP = High, both banks are precharged regardless of A₁₁ (PALL). If AP = Low, a bank to be selected by A₁₁ is precharged (PRE). The Auto-precharge enters precharge mode at the end of burst mode of read or write without Precharge command assertion. This Auto-precharge is entered by AP = High when a read or write command is asserted. Refer to FUNCTION TRUTH TABLE.

AUTO-REFRESH (REF)

Auto-refresh uses the internal refresh address counter. The SDRAM Auto-refresh command (REF) generates Precharge command internally. All banks of SDRAM should be precharged prior to the Auto-refresh command. The Auto-refresh command should also be asserted every 15.6 μ s or a total 4096 refresh commands within a 64 ms period.

SELF-REFRESH ENTRY (SELF)

Self-refresh function provides automatic refresh by an internal timer as well as Auto-refresh and will continue the refresh function until cancelled by SELFX.

The Self-refresh is entered by applying an Auto-refresh command in conjunction with CKE = Low (SELF). Once SDRAM enters the self-refresh mode, all inputs except for CKE will be "don't care" (either logic high or low level state) and outputs will be in a High-Z state. During a Self-refresh mode, CKE = Low should be maintained. SELF command should only be issued after last read data has been appeared on DQ.

Note: When the burst refresh method is used, a total of 4096 auto-refresh commands within 4 ms must be asserted prior to the self-refresh mode entry.

SELF-REFRESH EXIT (SELFX)

To exit Self-Refresh mode, apply minimum tcksp after CKE brought high, and then the NOP command (NOP) or the Deselect command (DESL) should be asserted within minimum trc. Refer to Timing Diagram for the detail.

It is recommended to assert an Auto-refresh command just after the tRC period to avoid the violation of refresh period.

Note: When the burst refresh method is used, a total of 4096 auto-refresh commands within 4 ms must be asserted after the self-refresh exit.

MODE REGISTER SET (MRS)

The mode register of SDRAM provides a variety of different operations. The register consists of four operation fields; Burst Length, Burst Type, CAS latency, and Operation Code. Refer to MODE REGISTER TABLE in page 33.

The mode register can be programmed by the Mode Register Set command (MRS). Each field is set by the address line. Once a mode register is programmed, the contents of the register will be held until re-programmed by another MRS command (or part loses power). MRS command should only be issued on condition that all DQ is in Hi-Z.

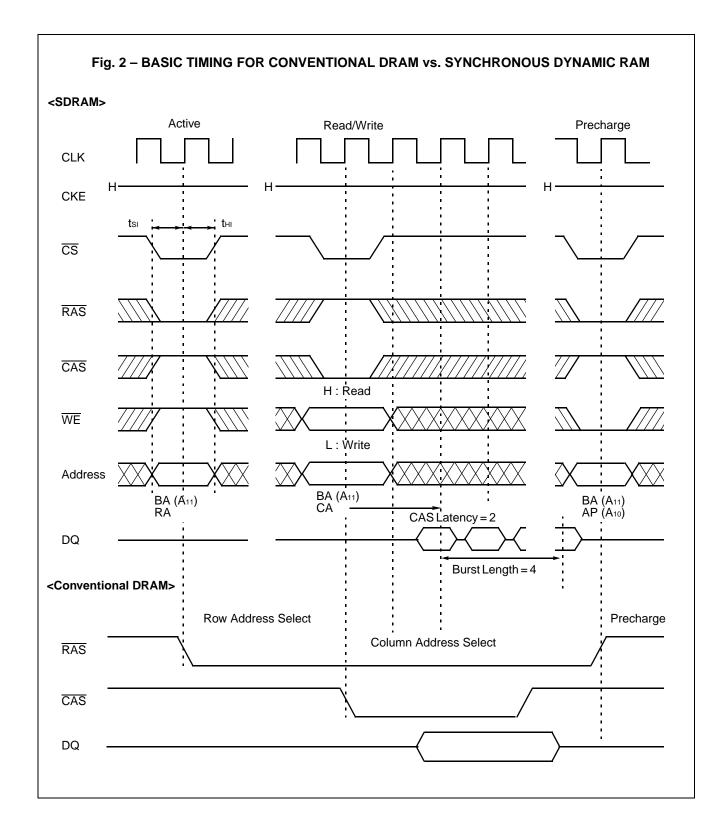
The condition of the mode register is undefined after the power-up stage. It is required to set each field after initialization of SDRAM. Refer to POWER-UP INITIALIZATION below.

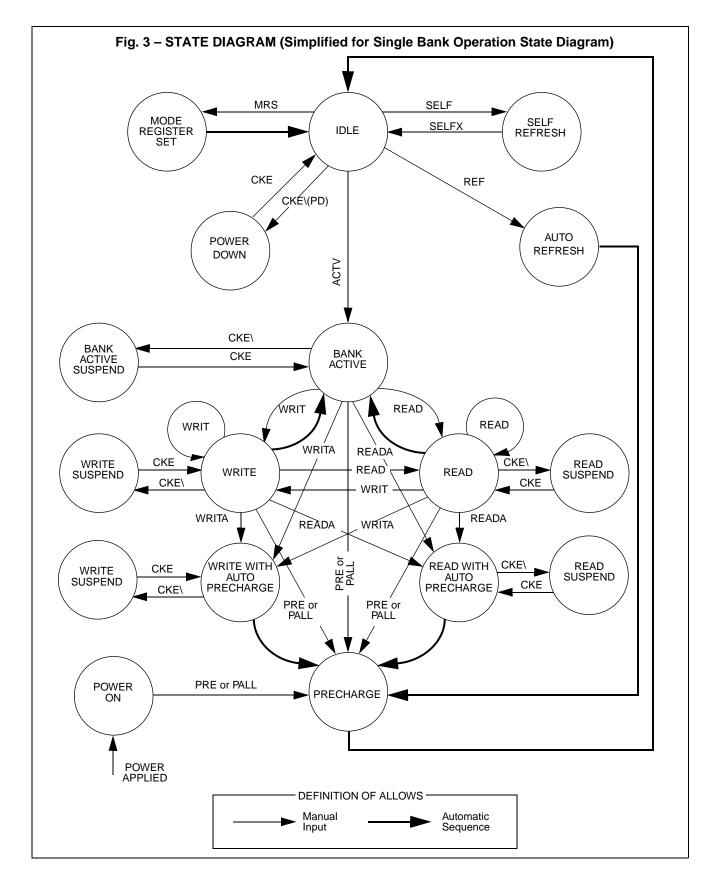
POWER-UP INITIALIZATION

The SDRAM internal condition after power-up will be undefined. It is required to follow the following Power On Sequence to execute read or write operation.

- 1. Apply power and start clock. Attempt to maintain either NOP or DESL command at the input.
- 2. Maintain stable power, stable clock, and NOP condition for a minimum of 200 μ s.
- 3. Precharge all banks by Precharge (PRE) or Precharge All command (PALL).
- 4. Assert minimum of 2 Auto-refresh command(REF).
- 5. Program the mode register by Mode Register Set command(MRS).

In addition, it is recommended DQML/DQMU and CKE to track Vcc to insure that output is High-Z state. The Mode Register Set command (MRS) can be set before 2 Auto-refresh command (REF).





■ 1 BANK OPERATION COMMAND TABLE

MINIMUM CLOCK LATENCY OR DELAY TIME FOR 1 BANK OPERATION

Second command (same bank) First command	MRS	ACTV	READ	READA	WRIT	WRITA	PRE	PALL	REF	SELF
MRS	t RSC	trsc					trsc	t RSC	t RSC	trsc
ACTV			t rcd	*4 t RCD	t rcd	*4 t RCD	tras	tras		
READ			1	1	*1 1	*1 1	1	1		
READA	*2 BL + t _{RP}	*2 BL + t _{RP}							*2 BL + t _{RP}	*2 BL + t _{RP}
WRIT			twr	twr	1	1	t dpl	t dpl		
WRITA	t dal	t dal							t dal	t dal
PRE	*3 trp	*3 trp					t RP	trp	*3 trp	*3 trp
PALL	*3 t RP	*3 t RP					t RP	trp	*3 t RP	*3 trp
REF	trc	trc					trc	trc	trc	trc
SELFX	trc	trc							trc	trc

Notes: *1. Assume no I/O conflict.

*2. If $t_{RP} \le t_{CK}$, minimum latency is a sum of BL + CL.

*3. Assume Output is in High-Z state.

*4. Assume tRAS is satisfied.



Illegal Command

■ MULTI BANK OPERATION COMMAND TABLE

MINIMUM CLOCK LATENCY OR DELAY TIME FOR 2 BANK OPERATION

Second command (opposite bank) First command	MRS	ACTV	READ	READA	WRIT	WRITA	PRE	PALL	REF	SELF
MRS	t RSC	trsc					trsc	t RSC	t RSC	trsc
ACTV		*1 t rrd	*2 1	*2 1	*2 1	*2 1	*7 1	tras		
READ		*1 1	*2 1	*2 1	*2 *3 1	*2 *3 1	*7 1	*8 1		
*9 READA	*1 *4 BL + t _{RP}	*1 1	1	1	1	1	1		*1 *4 BL + t _{RP}	*1 *4 BL + t _{RP}
WRIT		*1 1	*2 1	*2 1	*2 1	*2 1	*7 1	*8 1		
•9 WRITA	*1 *4 BL + t _{RP}	*1 1	1	1	1	1	1		*1 BL + 1 + t _{RP}	*1 BL + 1 + t _{RP}
PRE	*1 t RP	*1 1	*2 1	*2 1	*2 1	*2 1	1	tras	*1 t RP	*1 t RP
PALL	t RP	*1 t RP					1	1	*1 *6 t RP	*1 *6 t RP
REF	trc	t RC					t RC	t RC	trc	trc
SELFX	t RC	t RC							trc	trc

Notes: *1. Assume opposite bank is in idle state.

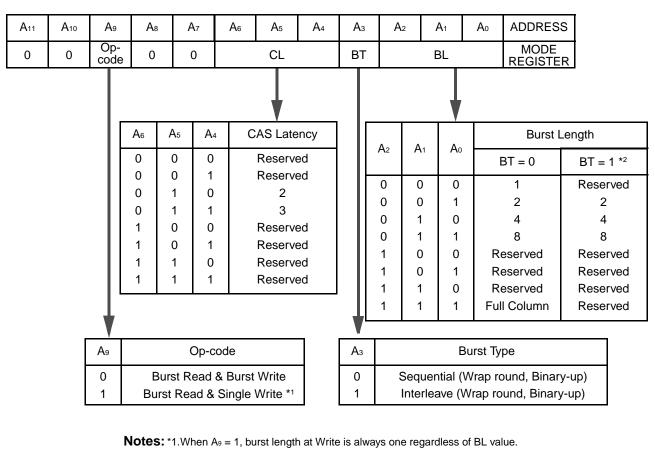
- *2. Assume opposite bank is in active state.
- *3. Assume no I/O conflict.
- *4. If $t_{RP} \le t_{CK}$, minimum latency is a sum of BL + CL.
- *5. Assume PALL command dose not affect any operation on opposite bank.
- *6. Assume Output is in High-Z state.
- *7. Assume tras of opposite bank is satisfied.
- *8. Assume $t_{RAS}(ACTV \text{ to PALL})$ is satisfied.
- *9. If opposite bank should be interrupted, tRAS of own bank is satisfied..



Illegal Command

■ MODE REGISTER TABLE

MODE REGISTER SET



*2.BL = 1 and Full Column are not applicable to the interleave mode.

■ ABSOLUTE MAXIMUM RATINGS (See WARNING)

Parameter	Symbol	Value	Unit
Voltage of Vcc Supply Relative to Vss	Vcc	-0.5 to +4.6	V
Voltage at Any Pin Relative to Vss	Vin, Vout	-0.5 to +4.6	V
Short Circuit Output Current	Ιουτ	-50 to +50	mA
Power Dissipation	PD	1.3	W
Storage Temperature	Tstg	-55 to +125	°C

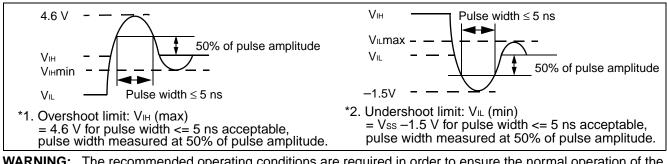
WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING CONDITIONS

(Referenced to Vss)

Parameter	Notes	Symbol	Min.	Тур.	Max.	Unit
	-60	Vcc, Vccq	3.15	3.3	3.6	V
Supply Voltage	-70/-80-/80L	Vcc, Vccq	3.0	3.3	3.6	V
	-70/-80-/80L Vcc, Vccq 3.0 3.3 3.6 Vss, Vssq 0 0 0 *1 Viн 2.0 — Vcc +	0	V			
Input High Voltage	*1	Vін	2.0	—	Vcc + 0.5	V
Input Low Voltage	*2	VIL	-0.5	—	0.8	V
Ambient Temperature		TA	0	—	70	°C

Notes:



WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within these recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

■ CAPACITANCE

				(T _A = 25°C, f = 1 MH			
Parameter	Symbol	Min.	Тур.	Max.	Unit		
Input Capacitance, Except for CLK	CIN1	2.5		5	pF		
Input Capacitance for CLK	CIN2	2.5	—	4	pF		
I/O Capacitance	Cı/o	4.0	—	6.5	pF		

■ DC CHARACTERISTICS

(At recommended operating conditions unless otherwise noted.) Notes *1, *2, and *3

D		Cumb al	Conditions	Va	lue	1.1
Pa	arameter	Symbol	Conditions	Min.	Max.	Unit
Output High Voltage	9	VOH(DC)	Iон = –2 mA	2.4	_	V
Output Low Voltage		Vol(DC)	lol = 2 mA	—	0.4	V
Input Leakage Curr	ent (Any Input)	lu	$0 V \le V_{IN} \le V_{CC};$ All other pins not under test = $0 V$	-5	5	μA
Output Leakage Cu	rrent	ILO	$0 V \le V_{IN} \le V_{CC};$ Data out disabled	-5	5	μA
	MB81F161622C-60		Burst: Length = 4,		150	
Operating Current (Average Power Supply Current)	MB81F161622C-70	-	tRc = min for BL = 4, tc κ = min,		130	
	MB81F161622C-80/-80L		One bank active,		110	-
(Average Power Supply Current)	*4 Reference Spec (100MHz @CL=3)	- Icc1s	Outputs open, Addresses changed up to 3-times during $t_{RC}(min)$, $0 V \le V_{IN} \le V_{CC}$ V_{CCQ} current is included.	_	130	– mA
		ICC2P	$\begin{array}{l} CKE = V_{IL},\\ AII \text{ banks idle,}\\ t_{CK} = min,\\ Power down mode,\\ 0 \ V \leq V_{IN} \leq V_{CC} \end{array}$	_	1	mA
	MB81F161622C -60/-70/-80		$CKE = V_{L}$, All banks idle,	_	1	mA
	MB81F161622C-80L	- ICC2PS	CLK = H or L, Power down mode, $0 V \le V_{IN} \le V_{CC}$	_	400	μA
Precharge	MB81F161622C-60		CKE = V⊮,		20	
Standby Current (Power Supply	MB81F161622C-70	-	All banks idle, tcκ = min,	_	20	
Current)	MB81F161622C-80/-80L		NOP commands only,		20	
	*4 Reference Spec (100MHz @CL=3)	- Icc2n	Input signals (except to CMD) are changed one times during 3 clock cycles, $0 V \le V_{IN} \le V_{CC}$	_	15	mA
		Icc2NS	$\begin{array}{l} CKE = V_{IH},\\ All \ banks \ idle,\\ CLK = H \ or \ L,\\ Input \ signals \ are \ stable,\\ 0 \ V \leq V_{IN} \leq V_{CC} \end{array}$	_	2	

(Continued)

D	arameter	Symbol	Conditions	Va	lue	Unit
Fc	ardineter	Symbol		Min.	Max.	Unit
Active Standby Current		Іссзр	$\begin{array}{l} CKE = V_{IL},\\ Any \text{ bank active,}\\ tck = min,\\ 0 \ V \leq V_{IN} \leq V_{CC} \end{array}$	_	1	mA
(Power Supply Current)	MB81F161622C -60/-70/-80	Іссзря	CKE = V⊫, Any bank active,	_	1	mA
	MB81F161622C-80L		CLK = H or L, $0 V \le V_{IN} \le V_{CC}$	_	400	μA
	MB81F161622C-60		CKE = VIH,	—	35	mA
	MB81F161622C-70	-	Any bank active, tcκ = min,		30	mA
	MB81F161622C-80/-80L	laan	NOP commands only,		30	mA
Active Standby Current	*4 Reference Spec (100MHz @CL=3)	Іссзи	Input signals (except to CMD) are changed one times during 3 clock cycles, $0 V \le V_{IN} \le V_{CC}$	_	20	mA
		Іссзия	$\begin{array}{l} CKE = V_{IH,} \\ Any \text{ bank active,} \\ CLK = H \text{ or } L, \\ 0 \ V \leq V_{IN} \leq V_{CC} \end{array}$	_	2	mA
	MB81F161622C-60		$t_{CK} = min,$		185	
Burst mode Current	MB81F161622C-70		Burst Length = 4, Outputs open,		160	
(Average Power	MB81F161622C-80/-80L	Icc4	Multiple-banks active, Gapless data,	—	145	mA
Supply Current)	Reference Spec *4 (100MHz @CL=3)		$0 V \le V_{IN} \le V_{CC}$ V _{CCQ} current is included.		35 m 35 m 30 m 30 m 20 m 2 m 185 m 160 m 145 m 120 80 70 70	-
	MB81F161622C-60				80	
Refresh Current #1	MB81F161622C-70	-	Auto-refresh; tск = min,		70	
(Average Power Supply Current)	MB81F161622C-80/-80L	Icc5	$t_{RC} = min,$	—	60	mA
	Reference Spec *4 (100MHz @CL=3)		$0 V \le V_{IN} \le V_{CC}$		55	
Refresh Current#2 (Average Power	MB81F161622C -60/-70/-80	Icc6	Self-refresh; tск = min,	_	1	mA
Supply Current)	MB81F161622C-80L	ICC6	$\begin{array}{l} CKE \leq 0.2 \ V, \\ 0 \ V \leq V_{IN} \leq V_{CC} \end{array}$	_	400	μA

Notes: *1. All voltages are referred to Vss.

*2. DC characteristics are measured after following the POWER-UP INITIALIZATION procedure.

*3. Icc depends on the output termination or load condition, clock cycle rate, signal clocking rate. The specified values are obtained with the output open and no termination register.

*4. This value is for reference only.

■ AC CHARACTERISTICS

(At recommended operating conditions unless otherwise noted.) Notes *1, *2, and *3

Parame	er Notes	Sym bol	MB81F1 -6	61622C 0		61622C 70	MB81F1 -80/-		Reference Spec ^{*4} (100MHz@CL=3)		Unit
		100	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Clock Period	CAS Latency = 2	tск2	—	_	10.5	_	12		15		ns
CIUCK Feriou	CAS Latency = 3	t скз	6.0	_	7.0		8		10		ns
Clock High Tim	ie *5	tсн	2.5	_	2.5	_	3		3		ns
Clock Low Tim	e *5	tc∟	2.5		2.5	_	3		3		ns
Input Setup Tir	ne *5	tsi	2		2	_	2.5		2.5		ns
Input Hold Tim	e *5	tнı	1		1	_	1		1	—	ns
Access Time from Clock (tck=min) *5,*6,*7	CAS Latency = 2	t _{AC2}	_			7	_	7		7	ns
	CAS Latency = 3	tасз	_	5.5	_	6	_	6		6	ns
Output in Low-	Z *5	t∟z	0		0	_	0		0		ns
Output in	CAS Latency = 2	t _{HZ2}	_		2	7	2	7	2	7	ns
High-Z *5,*8	CAS Latency = 3	t HZ3	2	5.5	2	6	2	6	2	6	ns
Output Hold	CAS Latency = 2	4	_		2	_	2		2		ns
Time *5,*7	CAS Latency = 3	tон	2		2	_	2		2		ns
Time between Auto-refresh command Interval *4		t REFI	_	15.6	_	15.6	_	15.6	_	15.6	μs
Transition Time)	t⊤	0.5	10	0.5	10	0.5	10	0.5	10	ns
CKE Setup tim Exit	e for Power Down *5	t CKSP	3		3	_	3		3	_	ns

BASE VALUES FOR CLOCK COUNT/LATENCY

Parameter	Notes	Symbol	MB81F161622C -60		MB81F161622C -70		MB81F161622C -80/-80L		Reference Speč ⁴ (100MHz@CL=3)		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
RAS Cycle Time *9		trc	54.0	_	63.0		72	_	80	_	ns
RAS Precharge Time		t RP	18.0	_	21.0		24		30	—	ns
RAS Active Time		tras	36	100000	42	100000	48	100000	50	100000	ns
RAS to CAS Delay Time		t RCD	18.0		21.0		24		30	_	ns
Write Recovery Time		twr	6.0		7.0		8		10	—	ns
Data-in to Precharge Lead Time		t dpl	6.0	_	7.0	_	8	_	10	_	ns
Data-in to Active/Refresh Command Period	CAS Latency = 2	tdal2			1cyc+t _{RP}	_	1cyc+t _{RP}	-	1cyc+t _{RP}	_	ns
	CAS Latency = 3	t DAL3	2cyc+t _{RP}		2cyc+t _{RP}	_	2cyc+t _{RP}	-	2cyc+t _{RP}	_	ns
Mode Register Set Cycle Time		trsc	12	_	14	_	16	_	20	_	ns
RAS to RAS Bank Active Delay Time		t rrd	12	_	14		16	_	20	_	ns

CLOCK COUNT FORMULA Note *10

 $Clock \ge \frac{Base Value}{Clock Period}$ (Round off a whole number)

LATENCY-FIXED VALUES

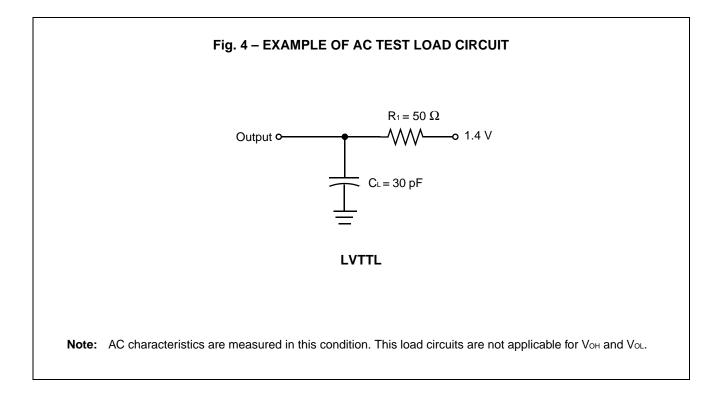
(The latency values on these parameters are fixed regardless of clock period.)

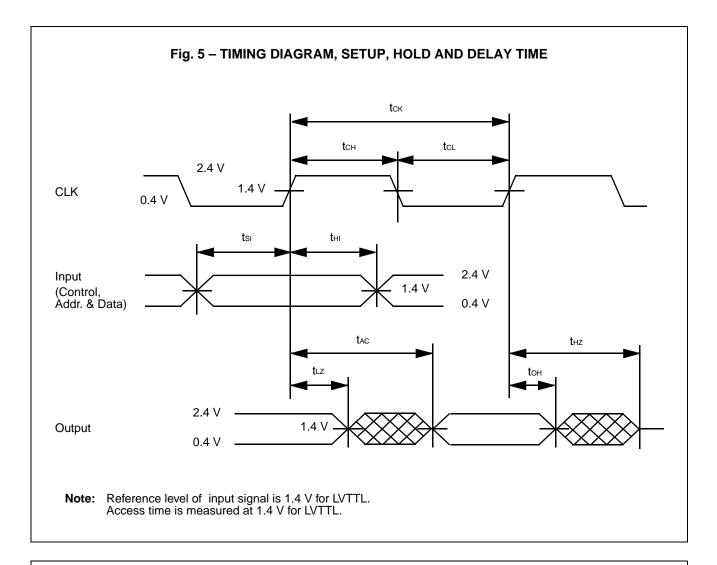
Parameter Notes		Sym- bol	MB81F161622C -60	MB81F161622C -70	MB81F161622C -80/-80L	Reference Spec ^{*4} (100MHz@CL=3)	Unit
CKE to Clock Disable		Іске	1	1	1	1	cycle
DQM to Output in High-Z		ldqz	2	2	2	2	cycle
DQM to Input Data Delay		Idqd	0	0	0	0	cycle
Last Output to Write Command Delay		Iowd	2 2		2	2	cycle
Write Command to Input Data Delay		ldwd	0	0	0	0	cycle
Precharge to Output in High-Z Delay	CL = 2	IROH2	—	2	2	2	cycle
	CL = 3	Ігонз	3	3	3	3	cycle
Burst Stop	CL = 2	Івзн2	—	2	2	2	cycle
Command to Output in High-Z Delay	CL = 3	Івѕнз	3	3	3	3	cycle
CAS to CAS Delay (min)		Ісср	1	1	1	1	cycle
CAS Bank Delay (min)		Ісвр	1	1	1	1	cycle

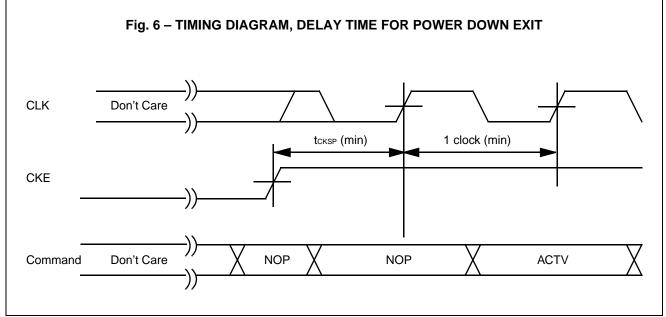
Notes: *1. AC characteristics are measured after following the POWER-UP INITIALIZATION procedure.

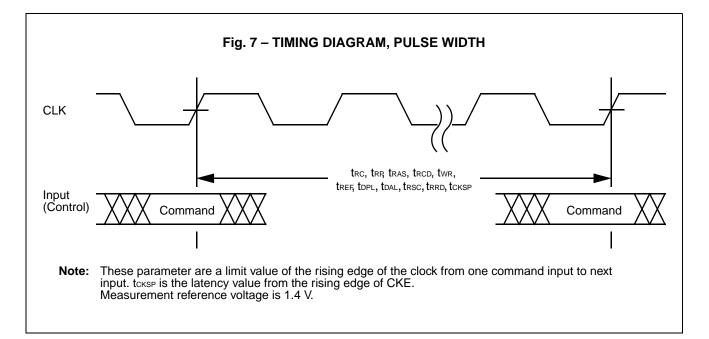
*2. AC characteristics assume $t_T = 1$ ns and 30 pF of terminated load.

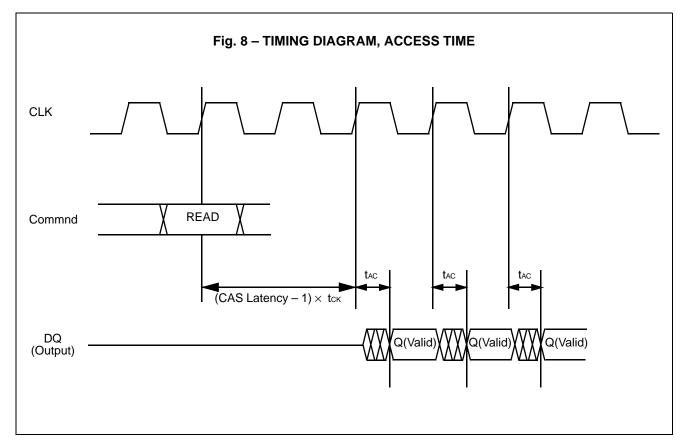
- *3. 1.4 V is the reference level for measuring timing of input signals. Transition times are measured between V_{IH} (min) and V_{IL} (max).
- *4. This value is for reference only.
- *5. If input signal transition time (t_T) is longer than 1 ns; [(t_T/2) 0.5] ns should be added to t_{AC} (max), t_{HZ} (max), and t_{CKSP} (min) spec values, [(t_T/2) 0.5] ns should be subtracted from t_{LZ} (min), t_{HZ} (min), and t_{OH} (min) spec values, and (t_T 1.0) ns should be added to t_{CH} (min), t_{CL} (min), t_{SI} (min), and t_{HI} (min) spec values.
- *6. tac also specifies the access time at burst mode.
- *7. t_{AC} and t_{OH} are the spec value under AC test load circuit shown in Fig. 4.
- *8. Specified where output buffer is no longer driven.
- *9. Actual clock count of trc (Irc) will be sum of clock count of tras (Iras) and trp (Irp).
- *10. All base values are measured from the clock edge at the command input to the clock edge for the next command input. All clock counts are calculated by a simple formula: clock count equals base value divided by clock period (round off to a whole number).



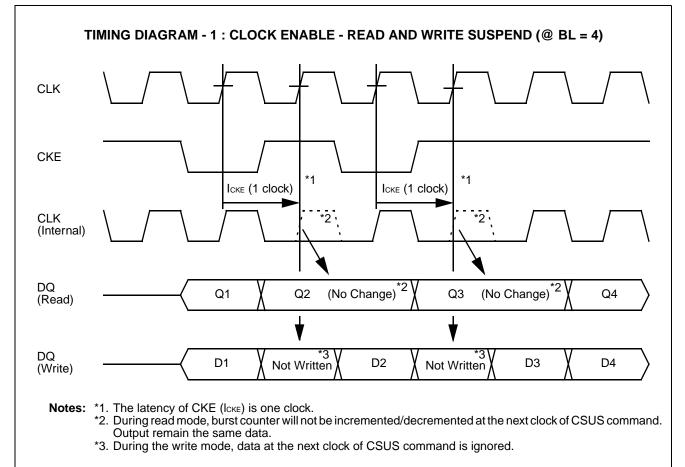


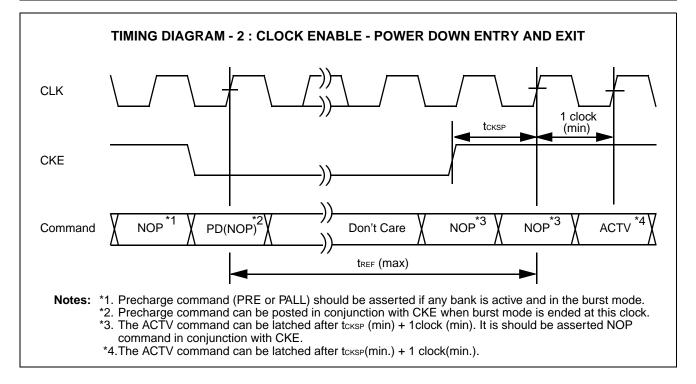


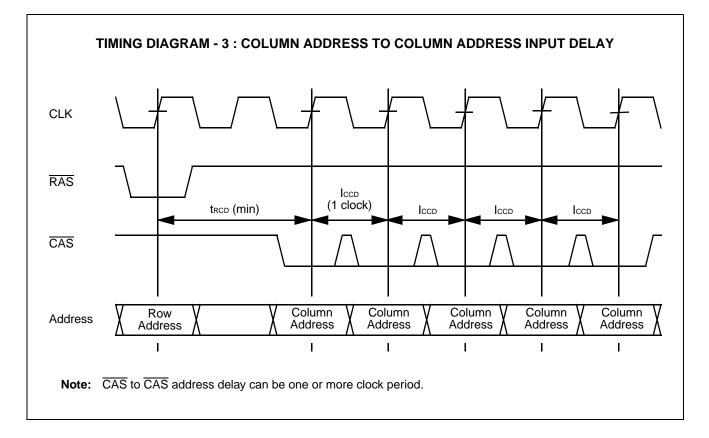


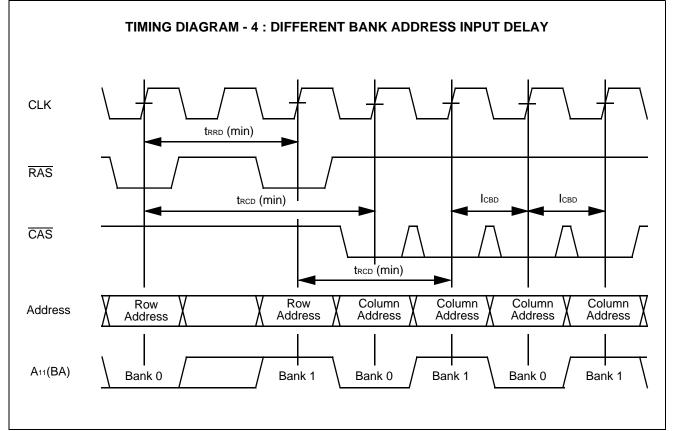


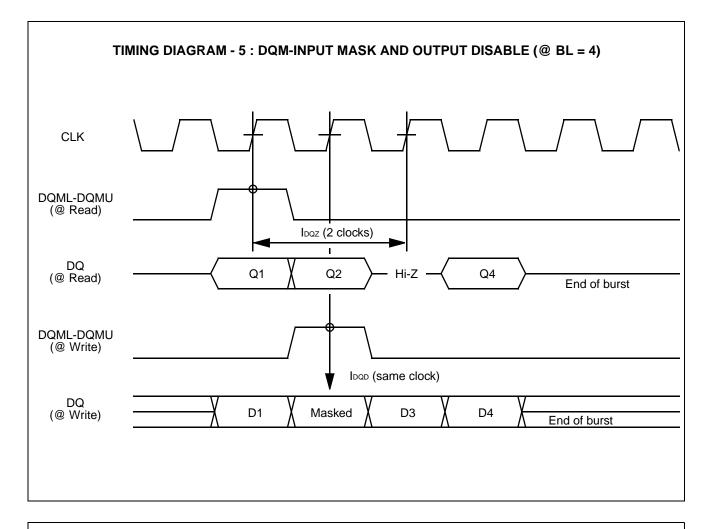
TIMING DIAGRAMS

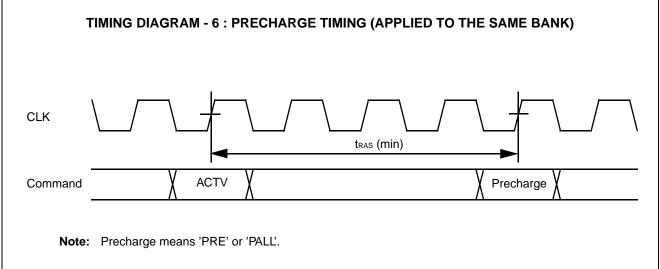


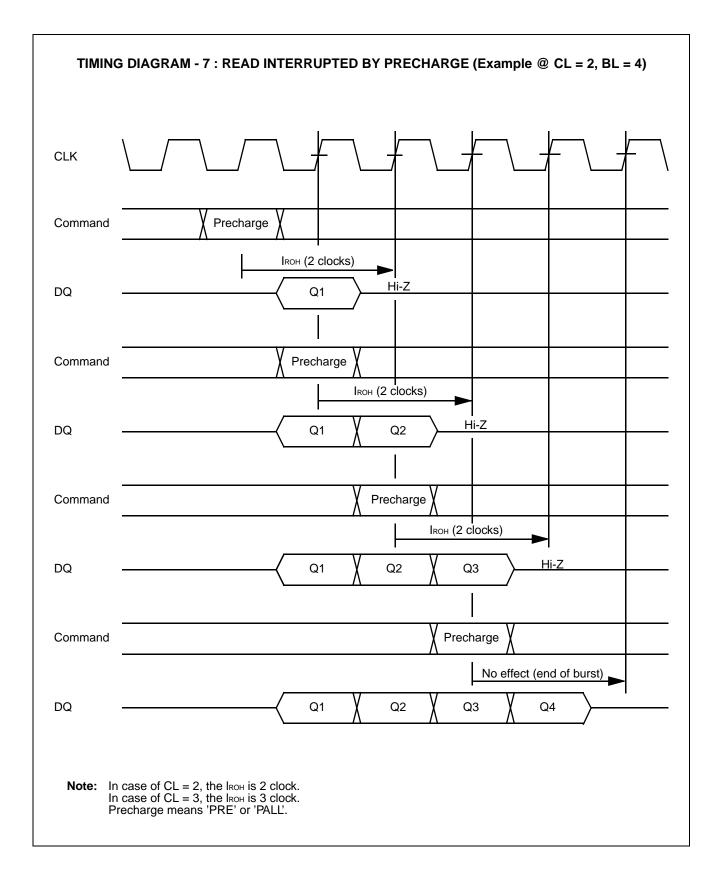


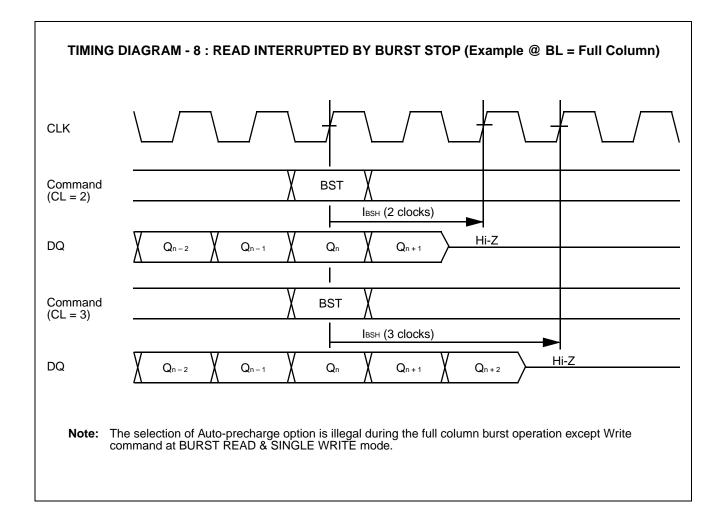


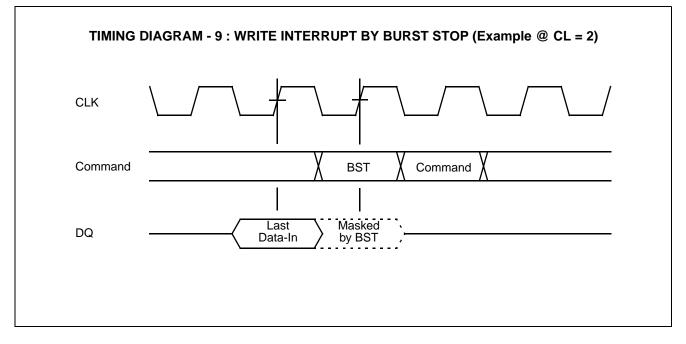


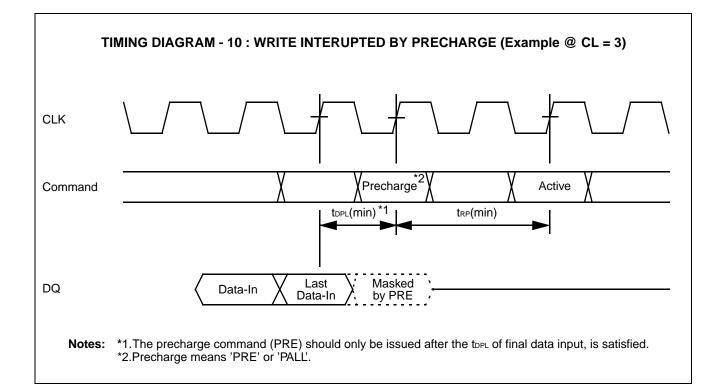


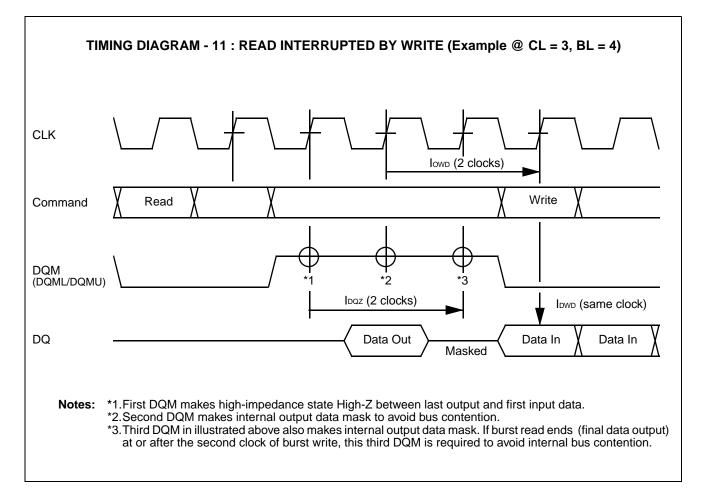


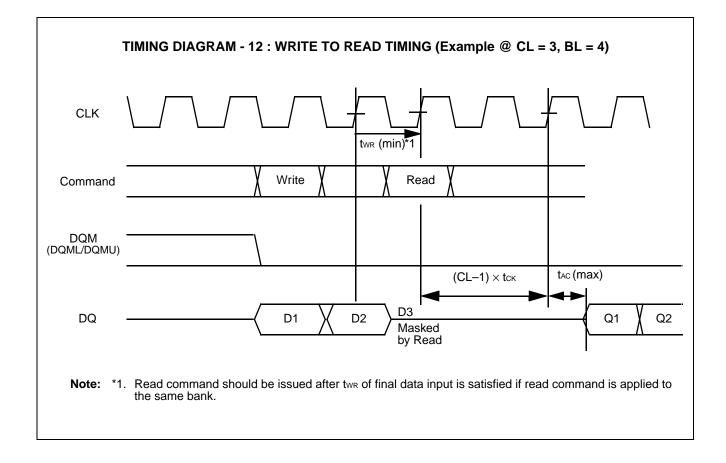


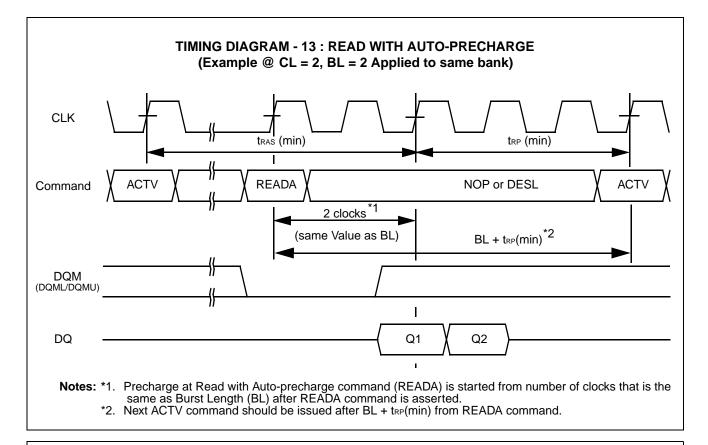


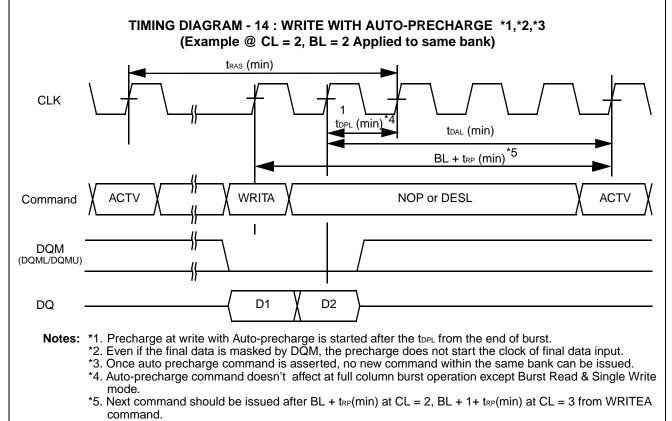


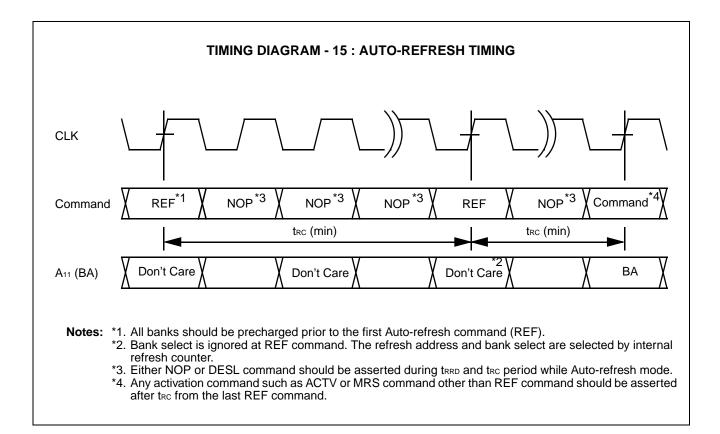


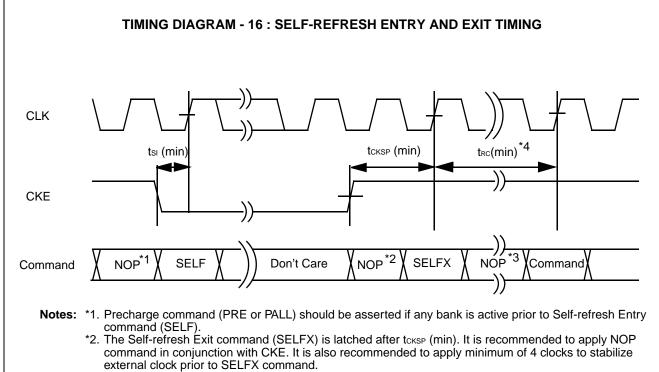




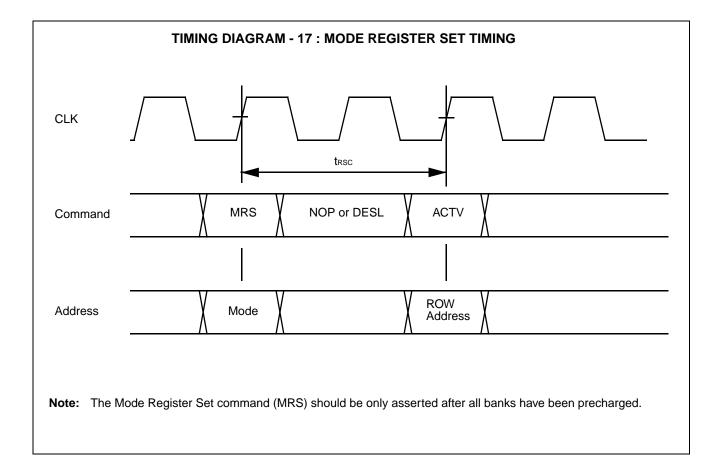




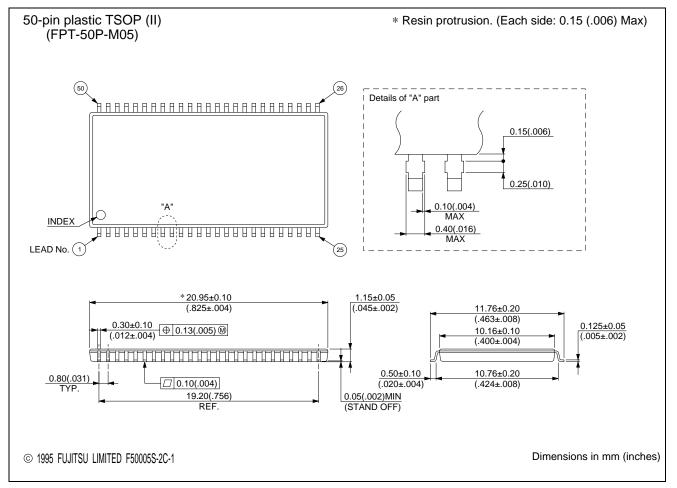




- *3. Either NOP or DESL command can be used during trc period.
- *4. CKE should be held High within trc(min) period after tcksp



■ PACKAGE DIMENSION



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